



Northeastern University
Silicon Valley

CALL FOR ABSTRACTS

Submission Deadline: September 7, 2016

IEEE SF Bay Area MEMS and Sensor Chapter

and

Northeastern University – Silicon Valley Campus

present a joint workshop on

Flexible / Printed / Fabric Sensors and Systems

Date: October 13, 2016 (Thursday)

Time: 9:00 AM to 5:00 PM

Location: Northeastern University – Silicon Valley Campus, 6024 Silver Creek Valley Rd, San Jose, CA 95138

General Chair: Roger Grace, Roger Grace Associates; **Technical Chair:** Ramesh Ramadoss, IEEE.

Exhibits Chair: Brent Lunceford, IEEE; **Marketing Chair:** Rick Davis, Northeastern University.

Host: P. K. Agarwal, Regional Dean and CEO, Northeastern University – Silicon Valley Campus.

For further information, please visit: <http://www.northeastern.edu/siliconvalley/campus-events/>

In recent years, there has been an exponential growth in the field of flexible, printed and organic large-area electronics and sensors. These new printed electronics and sensors are fabricated on flexible plastic substrates, which offer advantages such as mechanical flexibility, light weight and low profile. The use of flexible plastic substrates enables low cost high-speed manufacturing of devices over large areas using printing technologies in a Roll-to-Roll production line. Targeted applications include wearables, environmental monitoring and eHealth.

Recently, the U.S. Department of Defense (DoD) awarded \$75M to FlexTech Alliance to establish and manage a San Jose-based hub and node approach to create a Manufacturing Innovation Institute (MII) for Flexible Hybrid Electronics (FHE MII). Additionally, the recent award of \$75M, again by the US DoD, with \$250M in matching grants from industry and academia for the creation of a research and development consortia headed by MIT for the development of "Functional Fabrics" has validated the potential of this technology to create "smart fabrics" for consumer and military wearable applications.

This one-day workshop aims to bring together experts and leaders in this field to the heart of Silicon Valley. The workshop venue will consist of presentations on the topics of printed/flexible/fabric sensors and accompanying electronics and the applications that they are currently enabling as well as their future application opportunities. The presentations will be followed by an interactive panel discussion on the future of this rapidly growing market and the potential barriers to their commercialization. Continental breakfast, lunch and the concluding evening networking mixer event will be integral parts of the event.

Abstracts of between 150 and 250 words on the following topics are solicited.

Topics include:

- Sensor technologies
- Sensor-based systems
- Integration issues
- Manufacturing processes
- Computer modeling
- Materials
- Packaging and Interconnects
- Applications

Please submit your abstract to

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